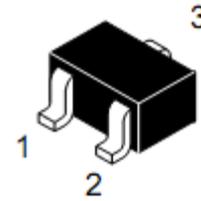
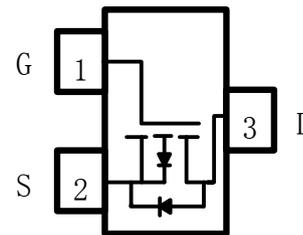


WPM1483
Single P-Channel, -12V, -5A, Power MOSFET
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

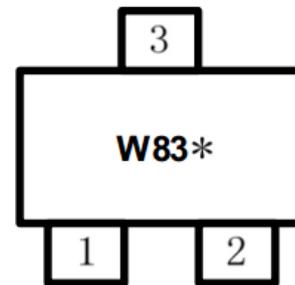
V _{DS} (V)	Typical R _{ds(on)} (Ω)
-12	0.031 @ V _{GS} = - 4.5V
	0.040 @ V _{GS} = - 2.5V
	0.056 @ V _{GS} = - 1.8V


SOT-23
Descriptions

The WPM1483 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM1483 is Pb-free and Halogen-free.


Pin configuration (Top view)
Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-23



W=Willsemi
83= Device Code
***= Month (A~Z)**
Marking

Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

Order information

Device	Package	Shipping
WPM1483-3/TR	SOT-23	3000/Reel&Tape

Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit	
Drain-Source Voltage	V_{DS}	-12	V	
Gate-Source Voltage	V_{GS}	± 8		
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-5	A
		$T_A=70^\circ\text{C}$	-4	
Pulsed Drain Current ^c	I_{DM}	-20		
Maximum Power Dissipation ^b	P_D	$T_A=25^\circ\text{C}$	1.2	W
		$T_A=70^\circ\text{C}$	0.8	
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$	
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$	

Thermal resistance ratings

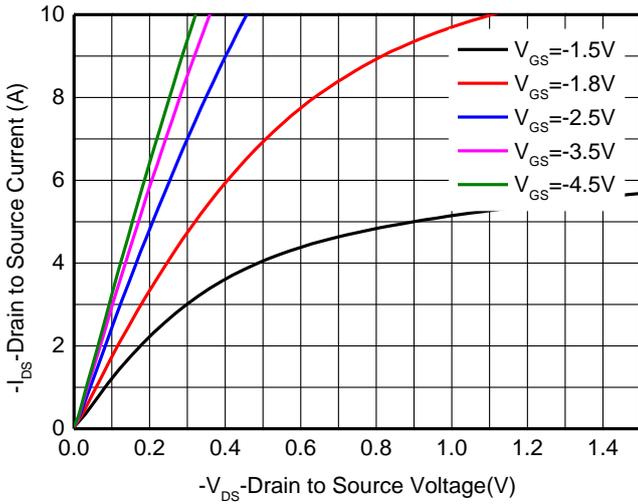
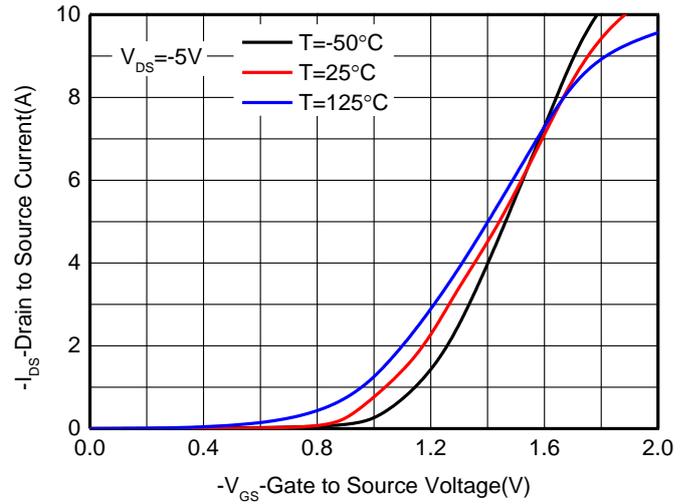
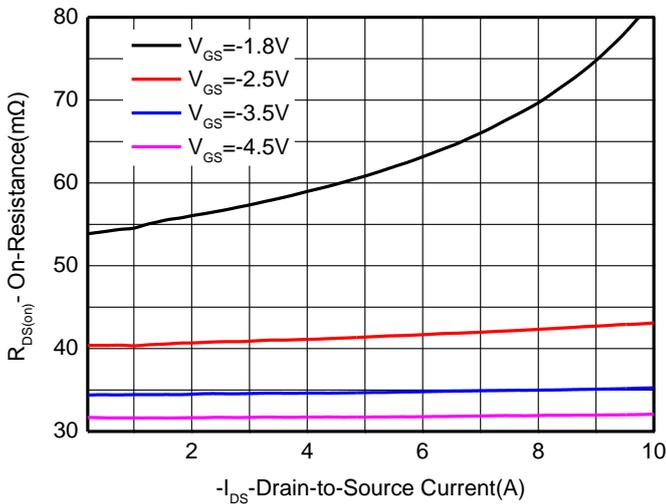
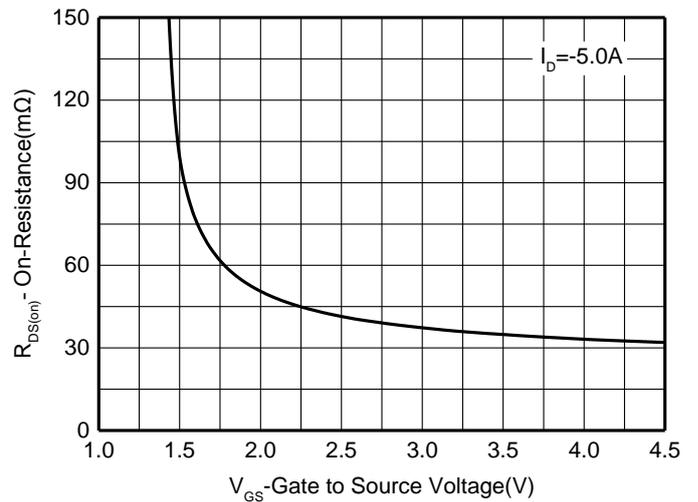
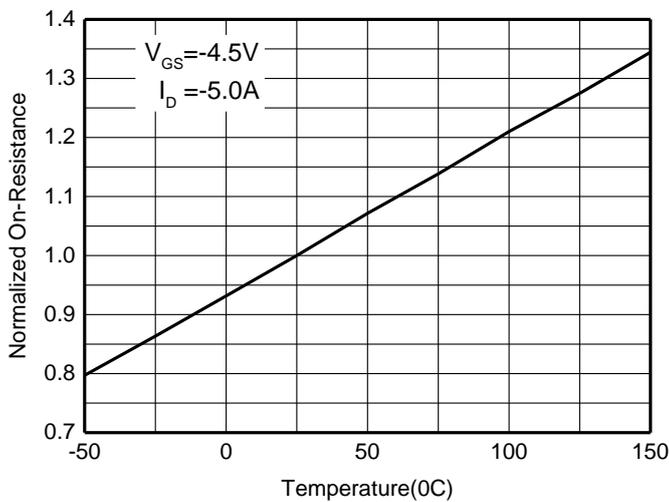
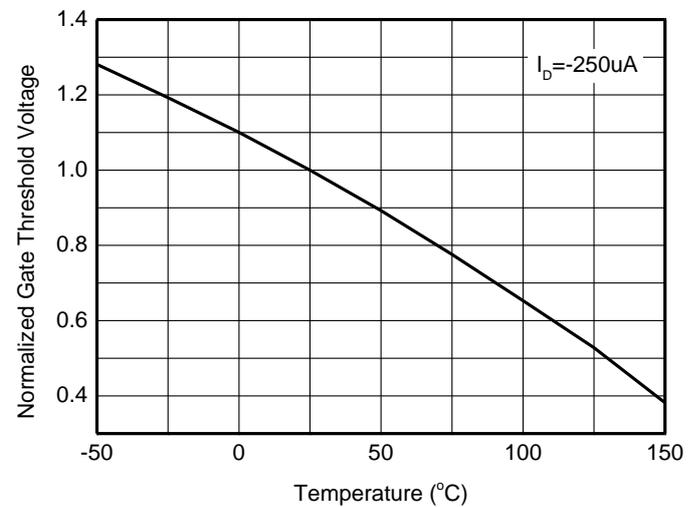
Single Operation					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10\text{ s}$	$R_{\theta JA}$	77	104	$^\circ\text{C/W}$
	Steady State		103	130	
Junction-to-Lead Thermal Resistance	Steady State	$R_{\theta JL}$	51	65	

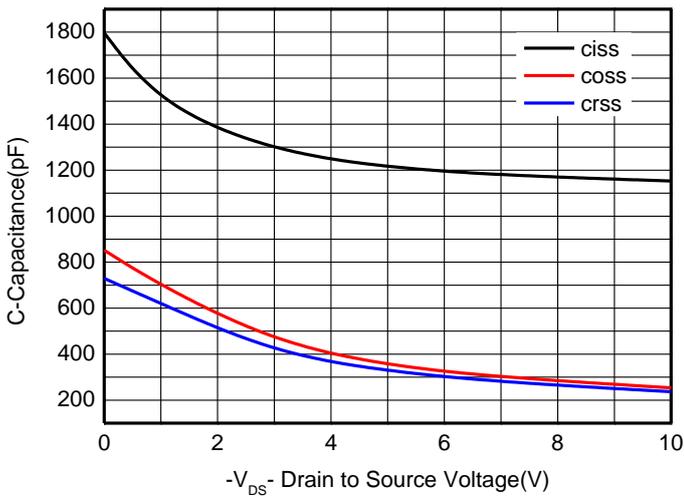
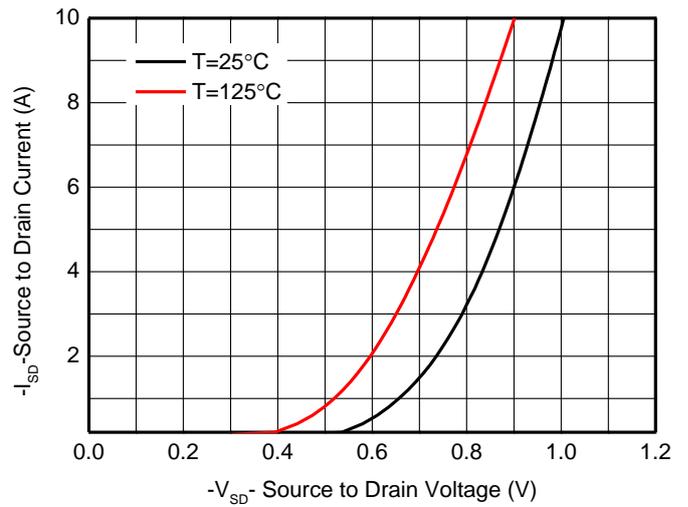
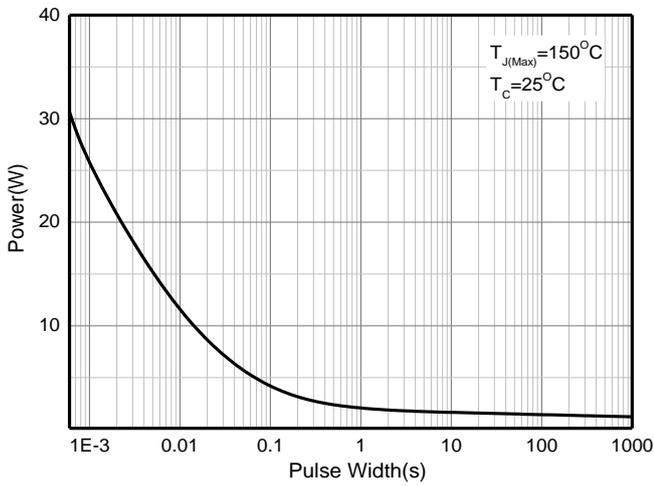
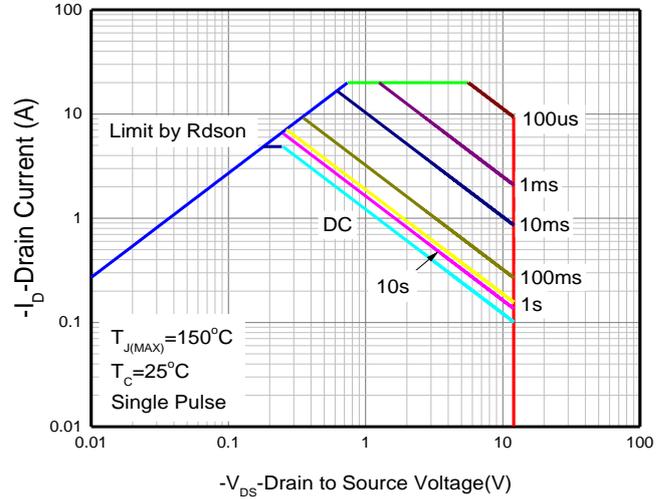
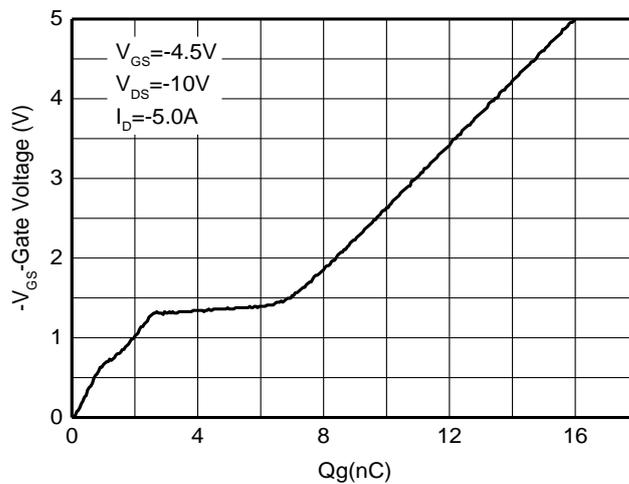
Note:

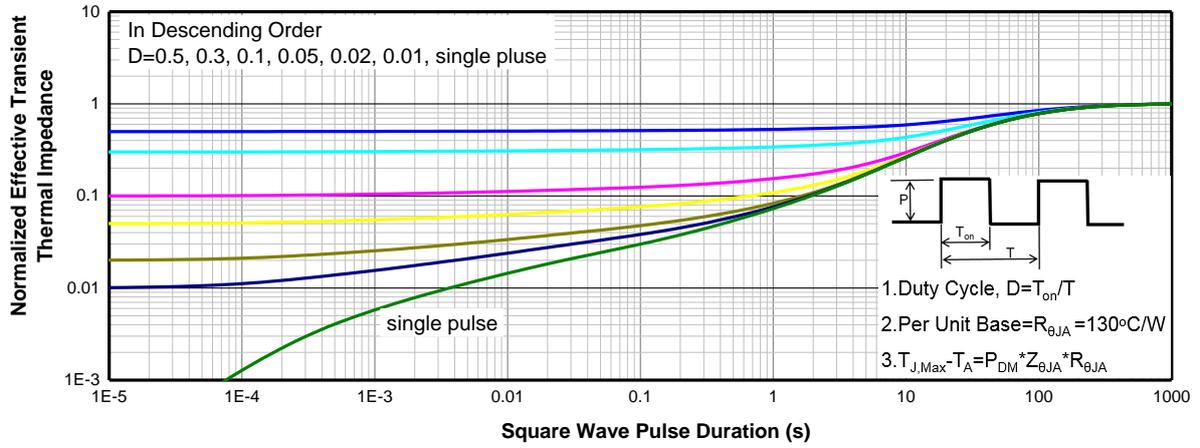
- The value of $R_{\theta JA}$ is measured with the device mounted on 1-inch² (6.45cm²) with 2oz.(0.071mm thick) Copper pad on a 1.5*1.5 inch², 0.06-inch thick FR4 PCB, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application is determined by the user's specific board design
- The power dissipation P_D is based on Junction-to-Ambient thermal resistance $R_{\theta JA}$ $t \leq 10\text{s}$ value and the $T_{J(\text{MAX})}=150^\circ\text{C}$.
- Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial $T_J = 25^\circ\text{C}$, the maximum allowed junction temperature of 150 $^\circ\text{C}$.
- The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

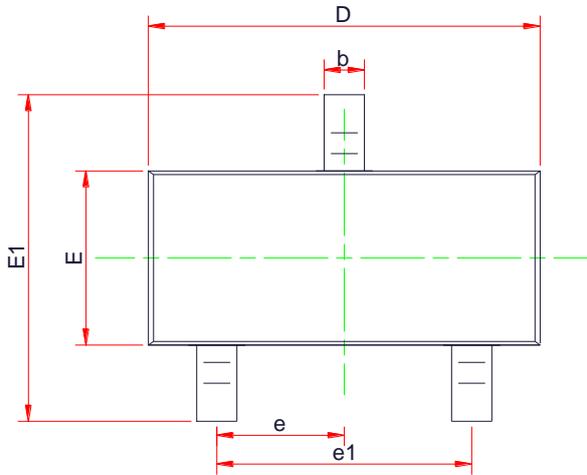
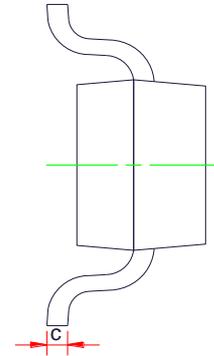
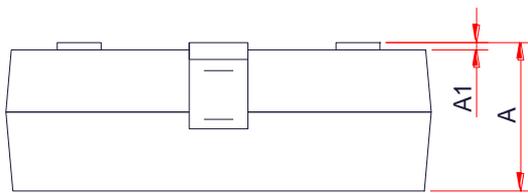
Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{ V}, I_D = -250\mu\text{A}$	-12			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
Gate-to-source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 8\text{ V}$			± 1	μA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-0.45	-0.55	-0.85	V
Drain-to-source On-resistance ^{b, c}	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}, I_D = -5.0\text{ A}$		31	37	m Ω
		$V_{GS} = -2.5\text{ V}, I_D = -3.0\text{ A}$		40	55	
		$V_{GS} = -1.8\text{ V}, I_D = -2.0\text{ A}$		56	88	
Forward Trans conductance	g_{fs}	$V_{DS} = -5.0\text{ V}, I_D = -2.0\text{ A}$		8.5		S
CAPACITANCES, CHARGES						
Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz},$ $V_{DS} = -10\text{ V}$		1152		pF
Output Capacitance	C_{OSS}			253		
Reverse Transfer Capacitance	C_{RSS}			236		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -4.5\text{ V},$ $V_{DD} = -10\text{ V},$ $I_D = -5.0\text{ A}$		14.6		nC
Threshold Gate Charge	$Q_{G(TH)}$			1.35		
Gate-to-Source Charge	Q_{GS}			2.3		
Gate-to-Drain Charge	Q_{GD}			5.7		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = -4.5\text{ V},$ $V_{DD} = -10\text{ V},$ $R_L = 3\ \Omega,$ $R_G = 6\ \Omega$		26		ns
Rise Time	t_r			23		
Turn-Off Delay Time	$t_d(OFF)$			68		
Fall Time	t_f			45		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = -1.0\text{ A}$		-0.8	-1.5	V

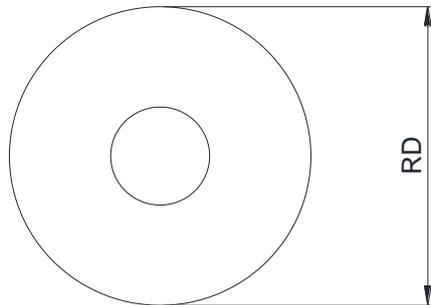
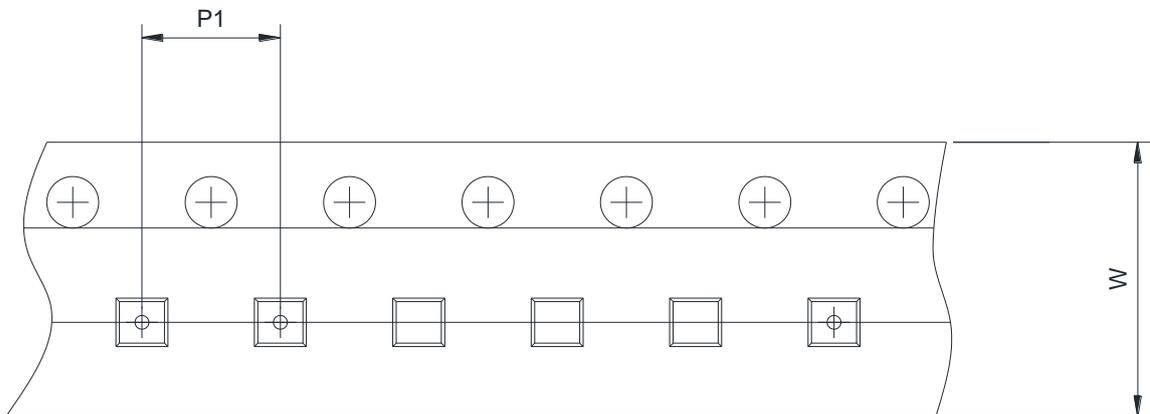
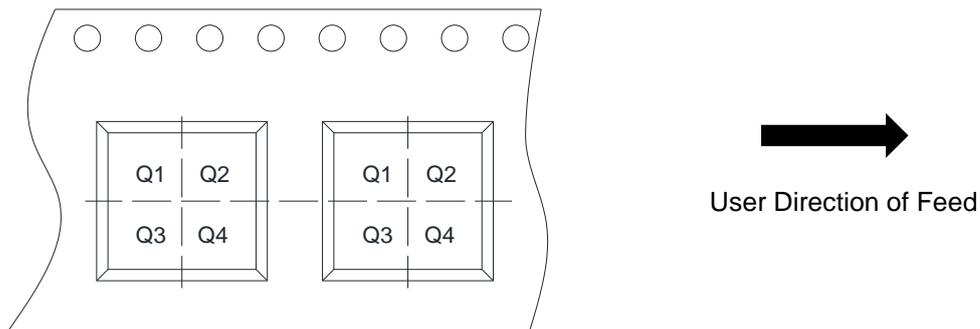
Typical Characteristics (Ta=25°C, unless otherwise noted)

Output characteristics

Transfer characteristics

On-Resistance vs. Drain current

On-Resistance vs. Gate-to-Source voltage

On-Resistance vs. Junction temperature

Threshold voltage vs. Temperature


Capacitance

Body diode forward voltage

Single pulse power

Safe operating power

Gate charge Characteristics

Transient thermal response (Junction-to-Ambient)


Package Outline Dimensions
SOT-23

TOP VIEW

SIDE VIEW

SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.89	1.10	1.30
A1	0.00	-	0.10
b	0.30	0.43	0.55
c	0.05	-	0.20
D	2.70	2.90	3.10
E	1.15	1.33	1.50
E1	2.10	2.40	2.70
e	0.95 Typ.		
e1	1.70	1.90	2.10

TAPE AND REEL INFORMATION
Reel Dimensions

Tape Dimensions

Quadrant Assignments For PIN1 Orientation In Tape


RD	Reel Dimension	<input checked="" type="checkbox"/> 7inch	<input type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input checked="" type="checkbox"/> 8mm	<input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input checked="" type="checkbox"/> 4mm <input type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input checked="" type="checkbox"/> Q3 <input type="checkbox"/> Q4